



piece
2015

R&D SPECIAL AWARD

Amor Zapanta
Jefferson Talledo
Bernie Chrisanto Ang

STMICROELECTRONICS, INC.

As **AUTHOR** of the technical paper entry entitled:

Understanding the Mechanical Behavior of Thin Packages During Die Attach Curing Process

Presented at the **25th ASEMPP National Technical Symposium**
thereby contributing greatly to the success of the event

On June 5, 2015 at World Trade Center Metro Manila, Pasay City, Philippines


DAN C. LACHICA
SEIPI President




CHANDRAMOGAN ANAMIRTHAM
HGST Philippines Corp. President


HGST
www.hgst.com


LITO MENA
ASEMPP Chairman

